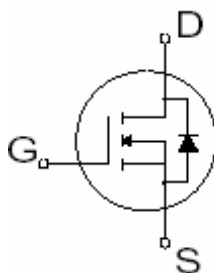


- Extremely high dv/dt capability
- Low Gate Charge Qg results in Simple Drive Requirement
- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitances
- Very good manufacturing repeatability



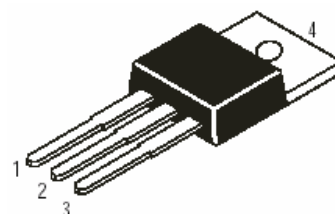
$$V_{DS} = 800V$$

$$I_{D25} = 2.4A$$

$$R_{DS(ON)} = 6.3 \Omega$$

Description

StarMOS is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimises the JFET effect, increases packing density and reduces the on-resistance. StarMOS also achieves faster switching speeds through optimised gate layout with planar stripe DMOS technology.



Pin1-Gate
Pin2-Drain
Pin1-Source

Application

- Switching application

Absolute Maximum Ratings

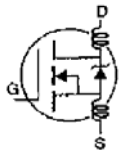
	Parameter	Max.	Units
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS}@10V$	2.4	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS}@10V$	1.52	
I_{DM}	Pulsed Drain Current ①	9.6	
$P_D@T_C=25^{\circ}C$	Power Dissipation	85	W
	Linear Derating Factor	0.68	W/°C
V_{GS}	Gate-to-Source Voltage	±30	V
E_{AS}	Single Pulse Avalanche Energy ②	180	mJ
I_{AR}	Avalanche Current ①	2.4	A
E_{AR}	Repetitive Avalanche Energy ①	8.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.0	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	°C
	Soldering Temperature, for 10 seconds	300(1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf.in(1.1N.m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case	—	—	1.47	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.5	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	62.5	

Electrical Characteristics @T_J=25 °C(unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
V _(BR) DSS	Drain-to-Source Breakdown Voltage	800	—	—	V	V _{GS} =0V, I _D =250μA
ΔV _(BR) DSS/ΔT _J	Breakdown Voltage Temp.Coefficient	—	0.9	—	V/°C	Reference to 25°C, I _D =250μA
R _{DS(on)}	Static Drain-to-Source On-resistance	—	4.9	6.3	Ω	V _{GS} =10V, I _D =1.2A ④
V _{GS(th)}	Gate Threshold Voltage	3.0	—	5.0	V	V _{DS} =V _{GS} , I _D =250μA
g _{fs}	Forward Transconductance	—	2.65	—	S	V _{DS} =50V, I _D =1.2A
I _{DSS}	Drain-to-Source Leakage current	—	—	25	μA	V _{DS} =800V, V _{GS} =0V
		—	—	250		V _{DS} =640V, V _{GS} =0V, T _J =150°C
I _{GSS}	Gate-to-Source Forward leakage	—	—	100	nA	V _{GS} =30V
	Gate-to-Source Reverse leakage	—	—	-100		V _{GS} =-30V
Q _g	Total Gate Charge	—	12	15	nC	I _D =2.4A
Q _{gs}	Gate-to-Source charge	—	2.6	—		V _{DS} =640V
Q _{gd}	Gate-to-Drain("Miller") charge	—	6.0	—		V _{GS} =10V
t _{d(on)}	Turn-on Delay Time	—	12	35	nS	V _{DD} =400V
t _r	Rise Time	—	30	70		I _D =2.4A
t _{d(off)}	Turn-Off Delay Time	—	25	60		R _G =25Ω
t _f	Fall Time	—	28	65		
L _D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm(0.25in.) from package and center of die contact
L _S	Internal Source Inductance	—	7.5	—		
C _{iss}	Input Capacitance	—	425	—	pF	V _{GS} =0V
C _{oss}	Output Capacitance	—	45	—		V _{DS} =25V
C _{rss}	Reverse Transfer Capacitance	—	5.5	—		f=1.0MHz


Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	2.4	A	MOSFET symbol showing the integral reverse p-n junction diode.
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	9.6		
V _{SD}	Diode Forward Voltage	—	—	1.4	V	T _J =25°C, I _S =2.4A, V _{GS} =0V ④
t _{rr}	Reverse Recovery Time	—	480	—	nS	T _J =25°C, I _F =2.4A
Q _{rr}	Reverse Recovery Charge	—	2.0	—	nC	di/dt=100A/μs ④
t _{on}	Forward Turn-on Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S + L _D)				

Notes:

① Repetitive rating;pulse width limited by
max.junction temperature(see figure 11)

② L = 59mH, I_{AS} = 2.4A, V_{DD} = 50V,
R_G = 25Ω, Starting T_J = 25°C

③ I_{SD} ≤ 2.4A, di/dt ≤ 200A/μS, V_{DD} ≤ V_(BR)DSS,
T_J ≤ 25°C

④ Pulse width ≤ 300 μS; duty cycle ≤ 2%